7-Stage Ripple Counter

The MC14024B is a 7-stage ripple counter with short propagation delays and high maximum clock rates. The Reset input has standard noise immunity, however the Clock input has increased noise immunity due to Hysteresis. The output of each counter stage is buffered.

Features

- Diode Protection on All Inputs
- Output Transitions Occur on the Falling Edge of the Clock Pulse
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range
- Pin-for-Pin Replacement for CD4024B
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (Voltages Referenced to VSS)

Cymphal	Parameter	Value	Unit
Symbol	Parameter	value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to V _{DD} + 0.5	٧
I _{in} , I _{out}	Input or Output Current (DC or Transient) per Pin	±10	mA
P _D	Power Dissipation, per Package (Note 1)	500	mW
T _A	Ambient Temperature Range	-55 to +125	ç
T _{stg}	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8-Second Soldering)	260	ç

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Temperature Derating:

Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

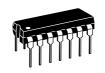
Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



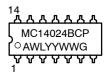
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http://onsemi.com

MARKING DIAGRAMS



PDIP-14 P SUFFIX **CASE 646**



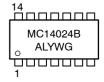


SOIC-14 **D SUFFIX** CASE 751A





SOEIAJ-14 **F SUFFIX CASE 965**



= Assembly Location

= Wafer Lot YY, Y = Year WW. W = Work Week = Pb-Free Package

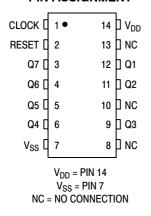
ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

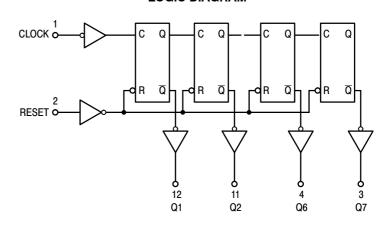
TRUTH TABLE

Clock	Reset	State		
0	0	No Change		
0	1	All Outputs Low		
1	0	No Change		
1	1	All Outputs Low		
	0	No Change		
	1	All Outputs Low		
~	0	Advance One Count		
~	1	All Outputs Low		

PIN ASSIGNMENT



LOGIC DIAGRAM



Q3 = PIN 9

Q4 = PIN 6

Q5 = PIN 5

ORDERING INFORMATION

Device	Package	Shipping [†]
MC14024BCPG	PDIP-14 (Pb-Free)	500 Units / Rail
MC14024BDG	SOIC-14 (Pb-Free)	55 Units / Rail
MC14024BDR2G	SOIC-14 (Pb-Free)	2500 / Tape & Reel
MC14024BFELG	SOEIAJ-14 (Pb-Free)	2000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

				- 55	5°C		25°C		125	s°C	
Characteristic		Symbol	V _{DD} Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
Output Voltage V _{in} = V _{DD} or 0	"0" Level	V _{OL}	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
V _{in} = 0 or V _{DD}	"1" Level	V _{OH}	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15	- - -	4.95 9.95 14.95	- - -	Vdc
Input Voltage ($V_O = 4.5 \text{ or } 0.5 \text{ Vdc}$) ($V_O = 9.0 \text{ or } 1.0 \text{ Vdc}$) ($V_O = 13.5 \text{ or } 1.5 \text{ Vdc}$)	"0" Level	V _{IL}	5.0 10 15	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	V _{IH}	5.0 10 15	3.5 7.0 11		3.5 7.0 11	2.75 5.50 8.25	- - -	3.5 7.0 11		Vdc
Output Drive Current $(V_{OH} = 2.5 \text{ Vdc})$ $(V_{OH} = 4.6 \text{ Vdc})$ $(V_{OH} = 9.5 \text{ Vdc})$ $(V_{OH} = 13.5 \text{ Vdc})$	Source	I _{OH}	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	- - -	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	- - - -	- 1.7 - 0.36 - 0.9 - 2.4	- - - -	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	I _{OL}	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4	- - -	mAdc
Input Current		l _{in}	15	_	±0.1	_	±0.00001	±0.1	_	±1.0	μAdc
Input Capacitance (V _{in} = 0)		C _{in}	-	-	-	-	5.0	7.5	-	-	pF
Quiescent Current (Per Package)		I _{DD}	5.0 10 15	- - -	5.0 10 20	- - -	0.005 0.010 0.015	5.0 10 20	- - -	150 300 600	μAdc
Total Supply Current (Note (Dynamic plus Quiesce Per Package) (C _L = 50 pF on all outp buffers switching)	ent,	Ι _Τ	5.0 10 15			$I_T = (0.$.31 μΑ/kHz) 1 .60 μΑ/kHz) 1 .89 μΑ/kHz) 1	f + I _{DD}			μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

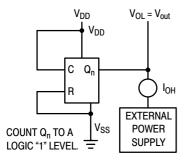
$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where: I_T is in μA (per package), C_L in pF, V = (V_{DD} – V_{SS}) in volts, f in kHz is input frequency, and k = 0.001.

SWITCHING CHARACTERISTICS (Note 5) (C $_L$ = 50 pF, T_A = 25 $^{\circ}C)$

Characteristic	Symbol	V _{DD}	Min	Typ (Note 6)	Max	Unit
Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) \text{ C}_{L} + 25 \text{ ns} \\ t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) \text{ C}_{L} + 12.5 \text{ ns} \\ t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) \text{ C}_{L} + 9.5 \text{ ns} \\ \end{cases}$	t _{TLH} , t _{THL}	5.0 10 15	- - -	100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q1 $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) \text{ C}_L + 295 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) \text{ C}_L + 117 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) \text{ C}_L + 85 \text{ ns}$ Clock to Q7 $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) \text{ C}_L + 915 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) \text{ C}_L + 367 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) \text{ C}_L + 275 \text{ ns}$ Reset to Q _n $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) \text{ C}_L + 415 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) \text{ C}_L + 217 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) \text{ C}_L + 155 \text{ ns}$	t _{PLH} , t _{PHL}	5.0 10 15 5.0 10 15 5.0 10	- - - - - -	380 150 110 1000 400 300 500 250 180	600 230 175 2000 750 565 800 400 300	ns
Clock Pulse Width	t _{WH}	5.0 10 15	500 165 125	200 60 40	- - -	ns
Reset Pulse Width	t₩H	5.0 10 15	600 350 260	375 200 150	- - -	ns
Reset Removal Time	t _{rem}	5.0 10 15	625 190 145	250 75 50	- - -	ns
Clock Input Rise and Fall Time	t _{TLH} , t _{THL}	5.0 10 15	- - -	- - -	1.0 8.0 200	s ms µs
Input Pulse Frequency	f _{cl}	5.0 10 15	- - -	2.5 8.0 12	1.0 3.0 4.0	MHz

^{5.} The formulas given are for the typical characteristics only at 25°C.
6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.





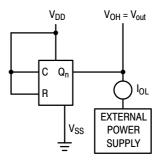


Figure 2. Typical Output Sink Characteristics Test Circuit

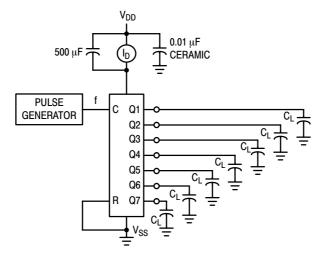


Figure 3. Power Dissipation Test Circuit

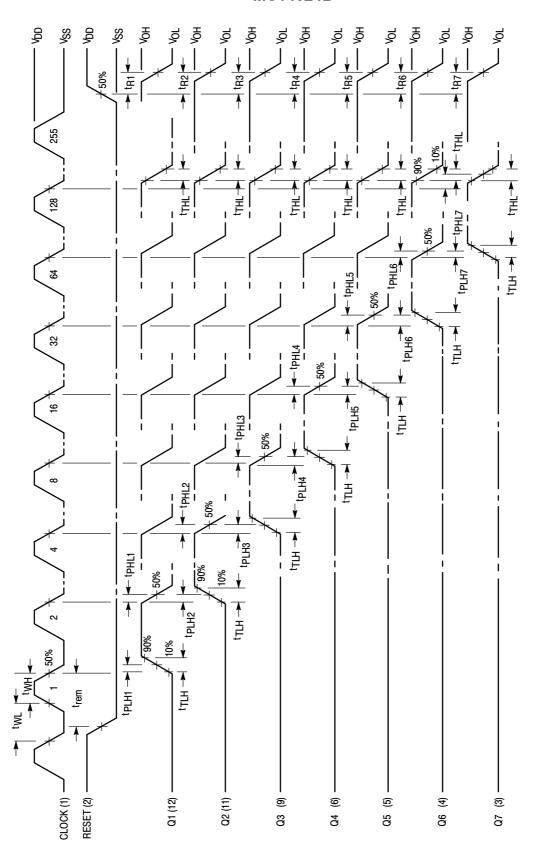
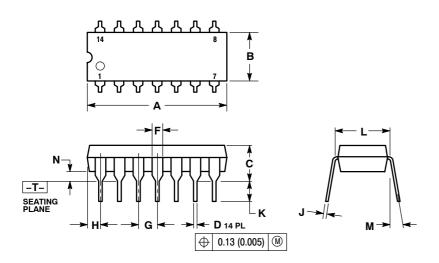


Figure 4. Functional Waveforms

PACKAGE DIMENSIONS

PDIP-14 CASE 646-06 **ISSUE P**

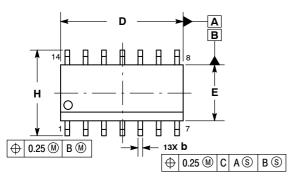


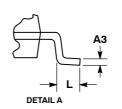
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

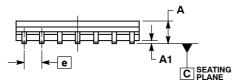
	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.715	0.770	18.16	19.56	
В	0.240	0.260	6.10	6.60	
С	0.145	0.185	3.69	4.69	
D	0.015	0.021	0.38	0.53	
F	0.040	0.070	1.02	1.78	
G	0.100	BSC	2.54 BSC		
Н	0.052	0.095	1.32 2.4		
J	0.008	0.015	0.20	0.38	
K	0.115	0.135	2.92	3.43	
L	0.290	0.310	7.37	7.87	
М		10 °		10 °	
N	0.015	0.039	0.38	1.01	

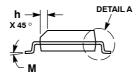
PACKAGE DIMENSIONS

SOIC-14 NB CASE 751A-03 **ISSUE K**









- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
 ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION & DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE PROTRUSION
 SHALL BE 0.13 TOTAL IN EXCESS OF AT
 MAXIMUM MATERIAL CONDITION.
 4. DIMENSIONS D AND E DO NOT INCLUDE
 MOLD PROTRUSIONS.
 5. MAXIMUM MOLD PROTRUSION 0.15 PER

 - 5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

	MILLIN	IETERS	INCHES		
DIM	MIN MAX		MIN	MAX	
Α	1.35	1.75	0.054	0.068	
A1	0.10	0.25	0.004	0.010	
АЗ	0.19	0.25	0.008	0.010	
b	0.35	0.49	0.014	0.019	
D	8.55	8.75	0.337	0.344	
Е	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050	BSC	
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.019	
L	0.40	1.25	0.016	0.049	
	0.0	5	0.0	-	

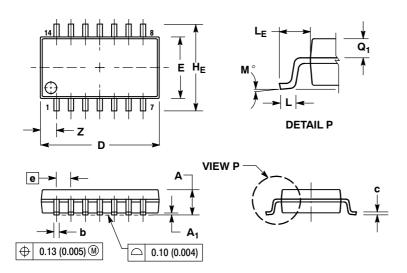
SOLDERING FOOTPRINT* 6.50 14X 1.18 1.27 **PITCH** 14X 0.58

DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOEIAJ-14 CASE 965-01 ISSUE B



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
 TALEM 1992
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.
- 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE
- PER SIDE.

 4. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.

 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.10	0.20	0.004	0.008
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	1.27 BSC		BSC
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
F	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10°
Q_1	0.70	0.90	0.028	0.035
Z		1.42		0.056

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